Product End-of-Life Disassembly Instructions

Product Category: Data Storage Devices
Marketing Name / Model [List multiple models if applicable.]
Ultrium 4, LTO 1760 half height external / EH920A, EB666X, EH922A, EB656X
Ultrium 3, LTO 920 half height external / EH842X, PD001X, EH848X & PD006X
Ultrium 2, LTO 448 half height external / DW017X, PD041X, DW086X & PD046X
Ultrium 1, LTO 232 half height external / DW065X & PD036X
Where X = any alphanumeric combination

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		5
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx screwdrivers	T-5, T-8 & T-10
Flathead screwdriver	NA
Scissors	NA
Adjustable spanner / pliers	Small
Crosshead screwdriver	1

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

Enclosure:

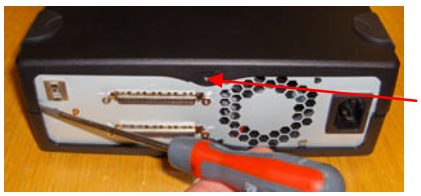
3.1.1. Remove the plastic lid and the base. Remove 1 x T-10 screw from the rear of the lid / chassis. Both the lid and the base are snap-fit. Use a flathead screwdriver to prize both the lid and the base from the metal chassis. See image 1.
3.1.2. Remove the mechanism. Disconnect the interface cables (SCSI / SAS), power and SCSI ID cables from the rear of the mechanism. Remove 2 x T-10 screws from the base of the chassis, 1 x T-10 screw from the front side and 1 x T-10 screw from the front of the chassis (next to front panel) and slide the mechanism back towards the rear of the chassis and out. See image 2.
3.1.3. Remove I/O PCA (> 10 square cm (SCSI enclosure only)). Remove 4 x securing nuts from the rear of the chassis (see image 3).
3.1.4. Remove SAS cable assembly (SAS enclosure only). Remove 2 x T-10 screws from the rear of the enclosure. Remove 4 x size '1' crosshead screws to remove the clamp from the SAS PCB. The PCB is > 10 square cm's. See image 4.
3.1.5. Remove the power supply PSU (PCB > 10 square cm's) and on/off PCB (PCB > 10 square cm's). Remove 1 x T-10 screw from the rear of the lid of the PSU and slide the lid back towards the rear of the chassis. (see image 5). Remove 4 x T-10 screws securing the PSU to the chassis and 1 x T-10 securing the on/off PCB. Use the clippers to remove the power cable (inlet to PSU), the fan cable and the SCSI ID cable. The Power Supply contains 5 x Electrolytic Capacitors measuring > 2.5 cm in height.

Mechanism:

3.1.6. Remove 2 x T-10 screws from either side of the mechanism to remove the wing brackets.
3.1.7. Clip off front panel
3.1.8. Remove lid by removing 4 x T-8 screws. See image 7.
3.1.9. Remove main PCA. Disconnect 3 x FPCs and lift out the PCA > 10 square cm. See image 8.
3.1.10. Remove the reel motor PCA. Remove take up reel – use a pair of scissors to cut the tape; remove grab stop; move carrier approximately 2 cm into the mechanism and slide out the reel motor PCA > 10 square cm. See images (9 - 12).

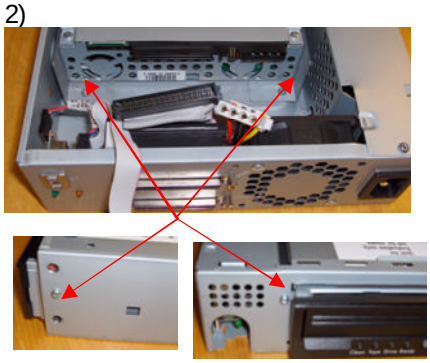
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1)



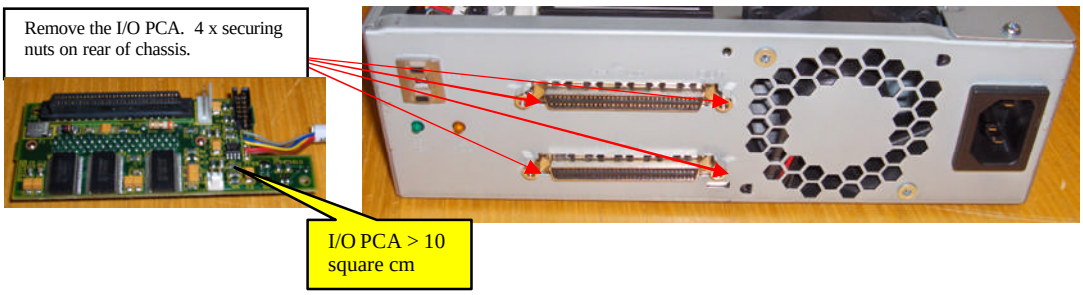
Remove T-10 screw and use flathead screwdriver to release the snap-fit clips securing the lid / base to the chassis.

2)

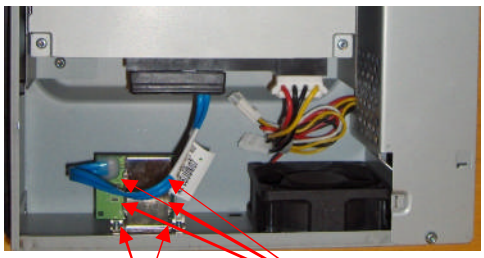


Remove 4 x T-10 screws to enable the mechanism to slide back into the chassis and out.

I/O Board removal. (3)



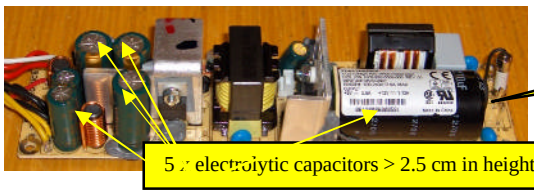
Remove the SAS cable Assembly (SAS enclosure only) (4)



2 x T-10 screws from rear of chassis

4 x size '1' crosshead screws from the underside of the PCA clamp

PSU & On / Off PCB removal. (5)



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Ultrium 1, 2 & 3 half height tape drive

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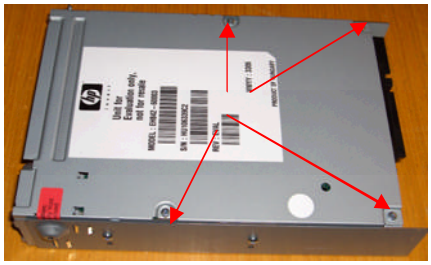
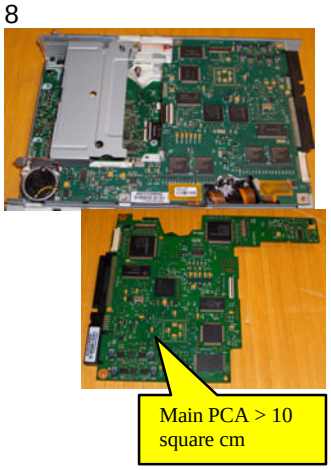


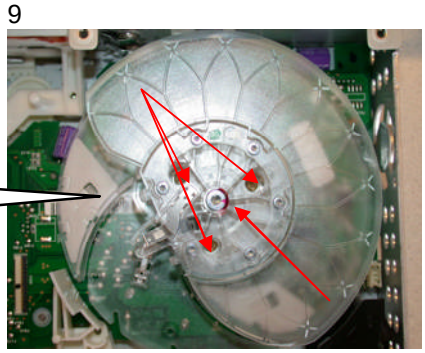
Remove 4 x T-8 screws to remove the lid.

8

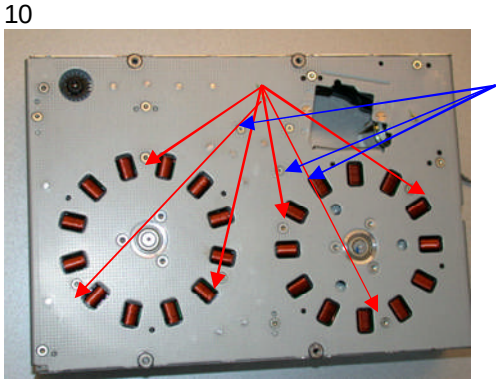


Main PCA > 10 square cm's

9

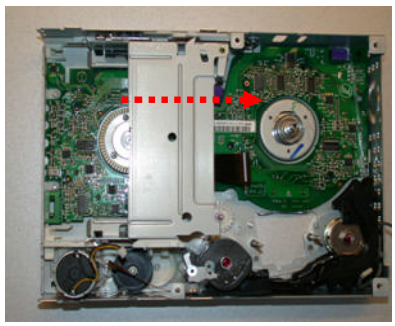


10



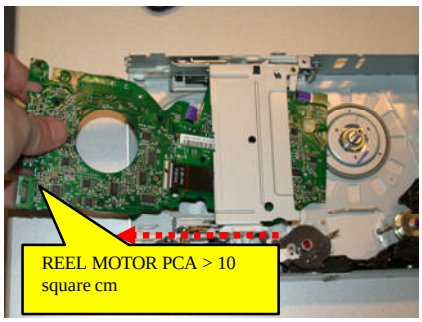
Remove 6 x T-8 and 3 x T-5 screws from base of mechanism to access the reel motor PCA.

11



Move carrier approximately 2 cm into the mechanism – directon of arrow.

12



Slide out the Reel motor PCA.